



PATENT

THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Salman Akram

Serial No.: 10/791,191

Filed: March 2, 2004

For: METHOD OF IMPROVING COPPER
INTERCONNECTS OF
SEMICONDUCTOR DEVICES FOR
BONDING

Confirmation No.: 1968

Examiner: L. Gurley

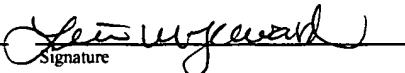
Group Art Unit: 2812

Attorney Docket No.: 2269-3854.3US
(98-0854.03/US)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

July 5, 2006
Date



Leta M. Howard
Name (Type/Print)

AMENDMENT

Mail Stop AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the Specification begin on page 3 of this paper.

Amendments to the Abstract appear on page 22 of this paper.

Serial No. 10/791,191

Amendments to the Claims are reflected in the listing of claims which begins on page 23 of this paper.

Amendments to the Drawings appear on page 26 of this paper and include both attached replacement sheets and annotated sheets showing changes.

Remarks begin on page 27 of this paper.